

# MECHANICAL CASE OUTLINE

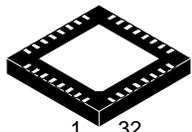
## PACKAGE DIMENSIONS

ON Semiconductor®

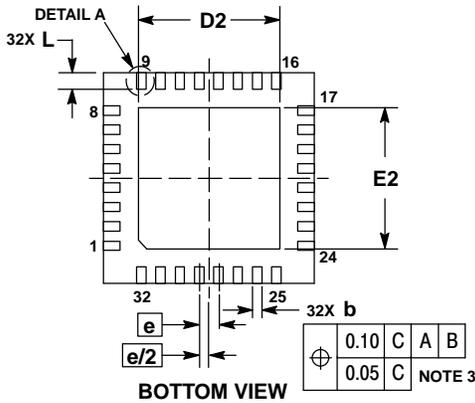
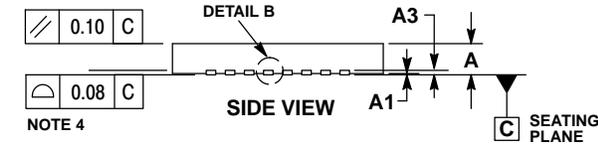
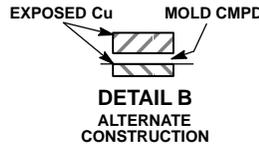
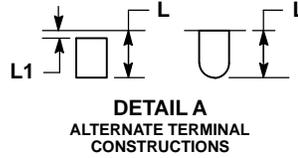
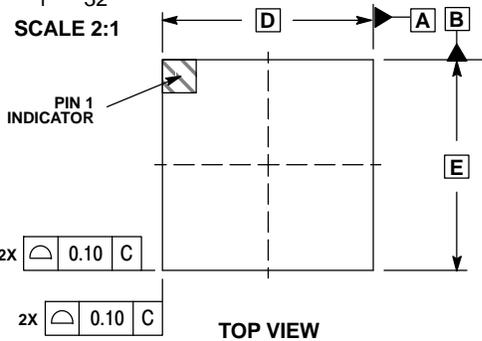


**QFN32 7x7, 0.65P**  
CASE 485ED  
ISSUE A

DATE 09 JUL 2015



SCALE 2:1

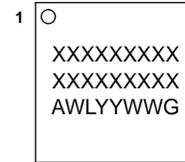


**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.25MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

MILLIMETERS		
DIM	MIN	MAX
A	0.80	0.90
A1	0.00	0.05
A3	0.20	REF
b	0.25	0.35
D	7.00	BSC
D2	4.60	4.80
E	7.00	BSC
E2	4.60	4.80
e	0.65	BSC
L	0.45	0.65
L1	0.00	0.15

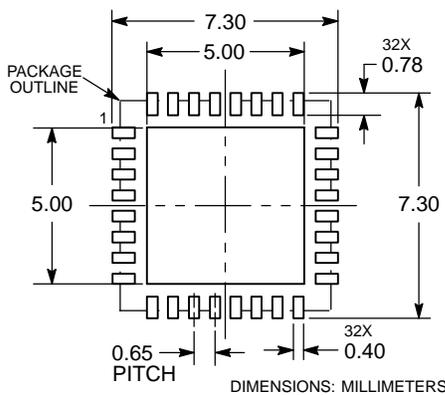
**GENERIC MARKING DIAGRAM\***



- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

**RECOMMENDED MOUNTING FOOTPRINT**



<b>DOCUMENT NUMBER:</b>	<b>98AON23217F</b>	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
<b>STATUS:</b>	<b>ON SEMICONDUCTOR STANDARD</b>	
<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	<b>QFN32 7X7, 0.65MM PITCH</b>	<b>PAGE 1 OF 2</b>

